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(54) CIRCUIT BOARD STRUCTURE AND METHOD OF MANUFACTURING THE SAME

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(57)ABSTRACT

A circuit board structure includes a rigid circuit board, a flexible circuit board, a plurality of conductive bumps, and a plurality of spacers. The rigid and flexible circuit boards are stacked one above the other. The conductive bumps are formed between the rigid and flexible circuit boards. The spacers are formed between the rigid and flexible circuit boards and spaced apart from the conductive bumps.



